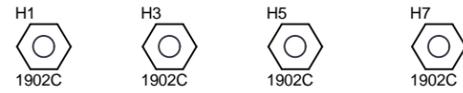
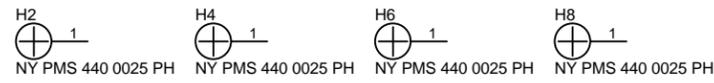


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Orderable: TPS92691EVM-752	Designed for: Public Release	Mod. Date: 1/24/2017
TID #: N/A	Project Title: Multiple Channel Temperature Sensing for Matrix LED	
Number: TIDA-01381	Rev: E1	Sheet Title: Boost LED Driver
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By: Cameron Phillips	File: TIDA-01381 Multi Channel Temp Sensing 2.Sch	Size: B
Engineer: Cameron Phillips	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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CAUTION HOT SURFACE



DANGER HIGH VOLTAGE

PCB Number: TIDA-01381  
PCB Rev: E1

PCB LOGO  
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PCB LOGO  
Pb-Free Symbol

PCB LOGO  
FCC disclaimer

ZZ1

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: <a href="#">TPS92691EVM-752</a>	Designed for: <a href="#">Public Release</a>	Mod. Date: 11/10/2016	
TID #: <a href="#">N/A</a>	Project Title: <a href="#">Multiple Channel Temperature Sensing for Matrix L</a>		
Number: <a href="#">TIDA-01381</a>	Rev: <a href="#">E1</a>	Sheet Title: <a href="#">Hardware</a>	
SVN Rev: <a href="#">Version control disabled</a>	Assembly Variant: <a href="#">001</a>	Sheet: <a href="#">2</a> of <a href="#">2</a>	
Drawn By: <a href="#">Cameron Phillips</a>	File: <a href="#">TIDA-01381 Multi Channel Temp Sensing Hardware SchDoc</a>	http://www.ti.com	
Engineer: <a href="#">Cameron Phillips</a>	Contact: <a href="#">http://www.ti.com/support</a>		© Texas Instruments 2016

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